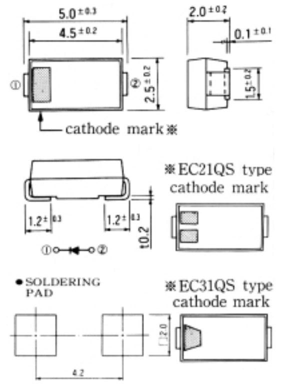
1A Avg.　400 Volts　FRED　EC11FS4

■最大定格　Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	400			V
非くり返しピーク逆電圧 Non-repetitive Peak Reverse Voltage	V_{RSM}	440			V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	Ta=25℃＊1	0.76	A
			Ta=26℃＊2	1	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	1.57			A
サージ順電流 Surge Forward Current	I_{FSM}	20　50Hz正弦半波，1サイクル，非くり返し 50Hz Half Sine Wave,1cycle, Non-repetitive			A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40～+150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40～+150			℃

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06g

■電気的・熱的特性　Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	T_j=25℃, V_{RM}=V_{RRM}		—	—	20	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	T_j=25℃, I_{FM}=1A		—	—	1.25	V
逆回復時間 Reverse Recovery Time	trr	I_{FM}=1A, -di/dt=50 A/μs, T_j=25℃		—	—	30	ns
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	Glass Epoxy Substrate Mounted＊1	—	—	157	℃/W
			Alumina Substrate Mounted＊2	—	—	108	℃/W

＊1:プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2 × 2 mm , Both Sides)
＊2:アルミナ基板実装/Alumina Substrate mounted (Soldering Lands= 2 × 2 mm , Both Sides)

■定格・特性曲線

FIG.1

順電圧特性
FORWARD CURRENT VS. VOLTAGE

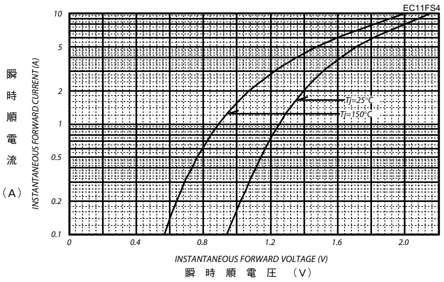


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

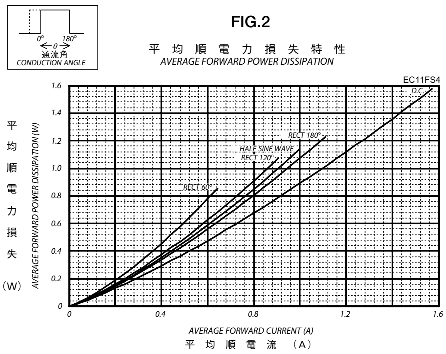


FIG.3

平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy Substrate Mounted(Soldering Land=2×2mm)

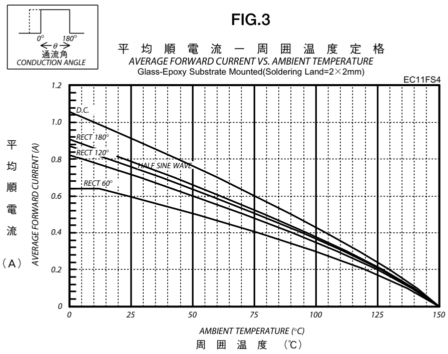


FIG.4

平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Alumina Substrate Mounted(Soldering Land=2×2mm)

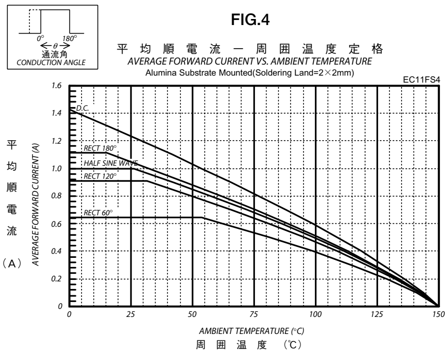


FIG.5

サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz,Half Sine Wave,Non-Repetitive,No Load